XL-0201UWC **Technical Data**

目录

Catalogue

电性参数
Electrical Characteristics.....3

典型特性曲线
Typical Characteristic Curves.....7

可靠性实验
Reliability Test Items And Conditions.....8

外形尺寸
Outline Dimensions.....9

包装
Packaging.....10

焊接指导
Guideline for Soldering.....12

使用注意事项
Precautions.....14

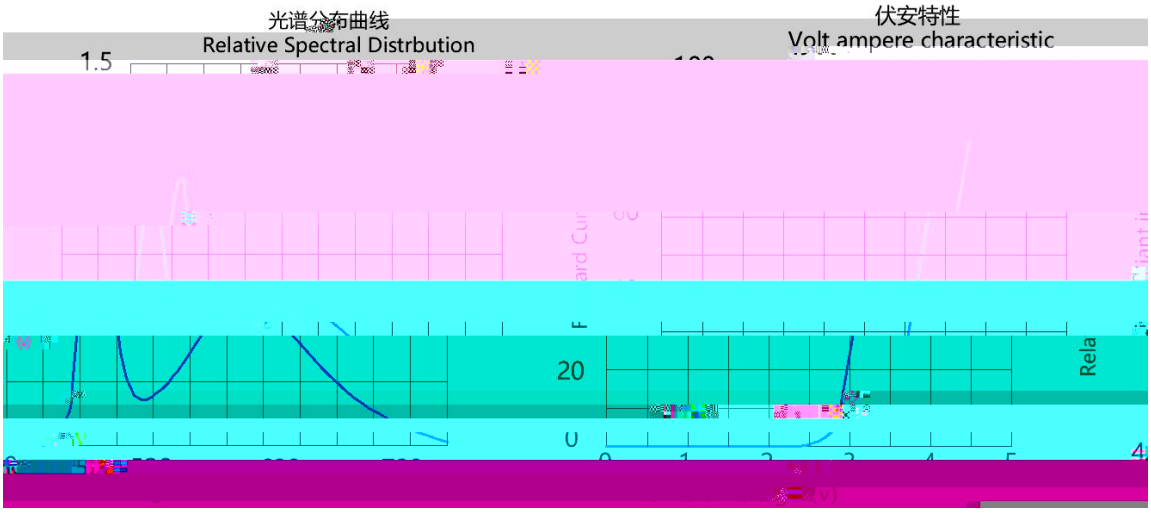
电性参数

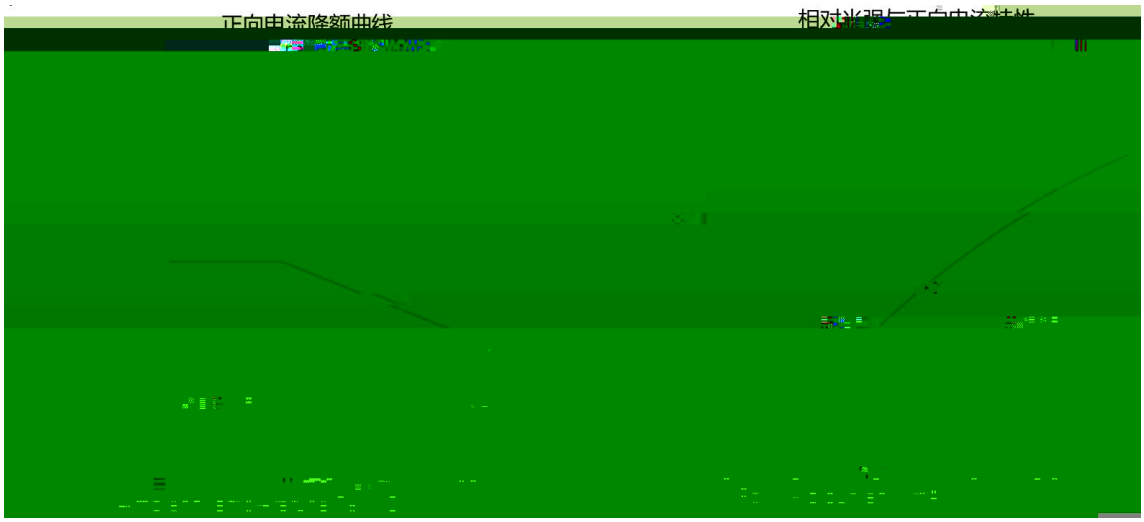
Electrical Characteristics

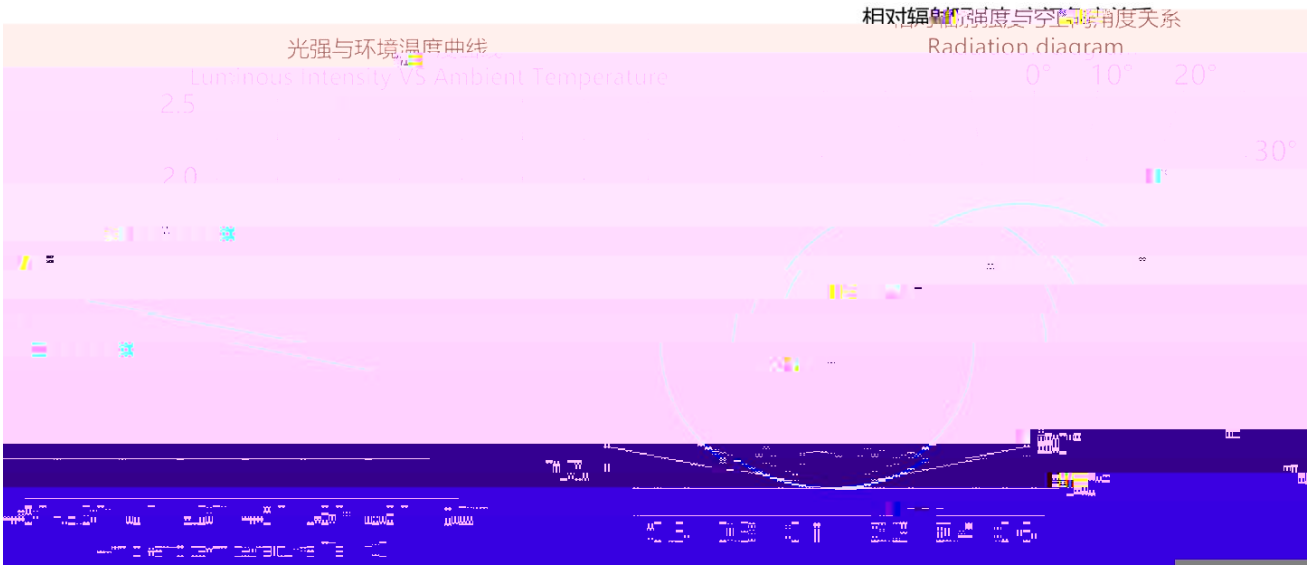
Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-Y	Bin Code	CIE-X	CIE-
	0.3099	0.3509		0.3202	0.3532		0.3290	0.3690		0.3381	0.3762		0.3005	0.3415
	0.3107	0.3450		0.3290	0.3614		0.3290	0.3614		0.3379	0.3689		0.3017	0.3360
F5	0.3201	0.3542	G5	0.3290	0.3690	H5	0.3379	0.3689	I5	0.3472	0.3764	E5	0.3107	0.3450
	0.3196	0.3602		0.3196	0.3602		0.3381	0.3762		0.3480	0.3840		0.3099	0.3509
	0.3107	0.3450												
F6														

典型特性曲线

Typical Characteristics Curves







Reliability experiment

Endurance test	Working life	Continuous lighting at the maximum rated current at room temperature:Test it at 20mA.	1000 hours	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
	High temperature and high humidity storage	IR-Reflow In-Board, 2 Times Ta= 85±5℃, RH= 90~95%	240hours (240hours)	MIL-STD-202F:103B JIS C 7021:B-11
	High-temperature storage	Ta= 85±5℃	1000 hours (-24℃ +72℃) -24hours+72hours	MIL-STD-883D:1008 JIS C 7021:B-10
	Low temperature storage	Ta= -40±5℃		JIS C 7021:B-12
Environmental testing	Cold and hot cycle	105℃ 25℃ -55℃ 25℃ 30mins 5mins 30mins 5mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010
	Hot and cold impact	IR-Reflow In-Board, 2 Times' 100±5℃ -40℃±5℃' 20mins' 20mins	100 100 Circles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	Anti-tin test	T.sol= 260±5℃	10±1secs 2 2times	MIL-STD-202F:210A MIL-STD-750D:2031 JIS C 7021:A-1
	Infrared reflowwelding There is lead process	heat up speed(183℃) 3℃/ keep temperature 125(±25)℃ 120 keep temperature183℃ 60-150 maximum temperature 235℃+5/-0℃ keep235℃+5/-0℃ 10-15 cooling rate 6℃/	--------	MIL-STD-750D:2031.2 J-STD-020C
	Infrared reflow welding Lead-free process	heat up speed(217℃) 3℃/ keep temperature 175(±25)℃ 180 keep temperature217℃ 60-120 maximum temperature 255℃+0/-5℃ keep255℃+0/-5℃ 5-10 cooling rate 6℃/	--------	MIL-STD-750D:2031.2 J-STD-020C
	Weldability test	Soldering temperature T.sol= 235±5℃ Immersion speed 25±2.5 mm/ 95% Tin loading rate 95% pad area Immersion time: 2±0.5 seconds	Immersion time 2±0.5	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2

外形尺寸

Outline Dimension

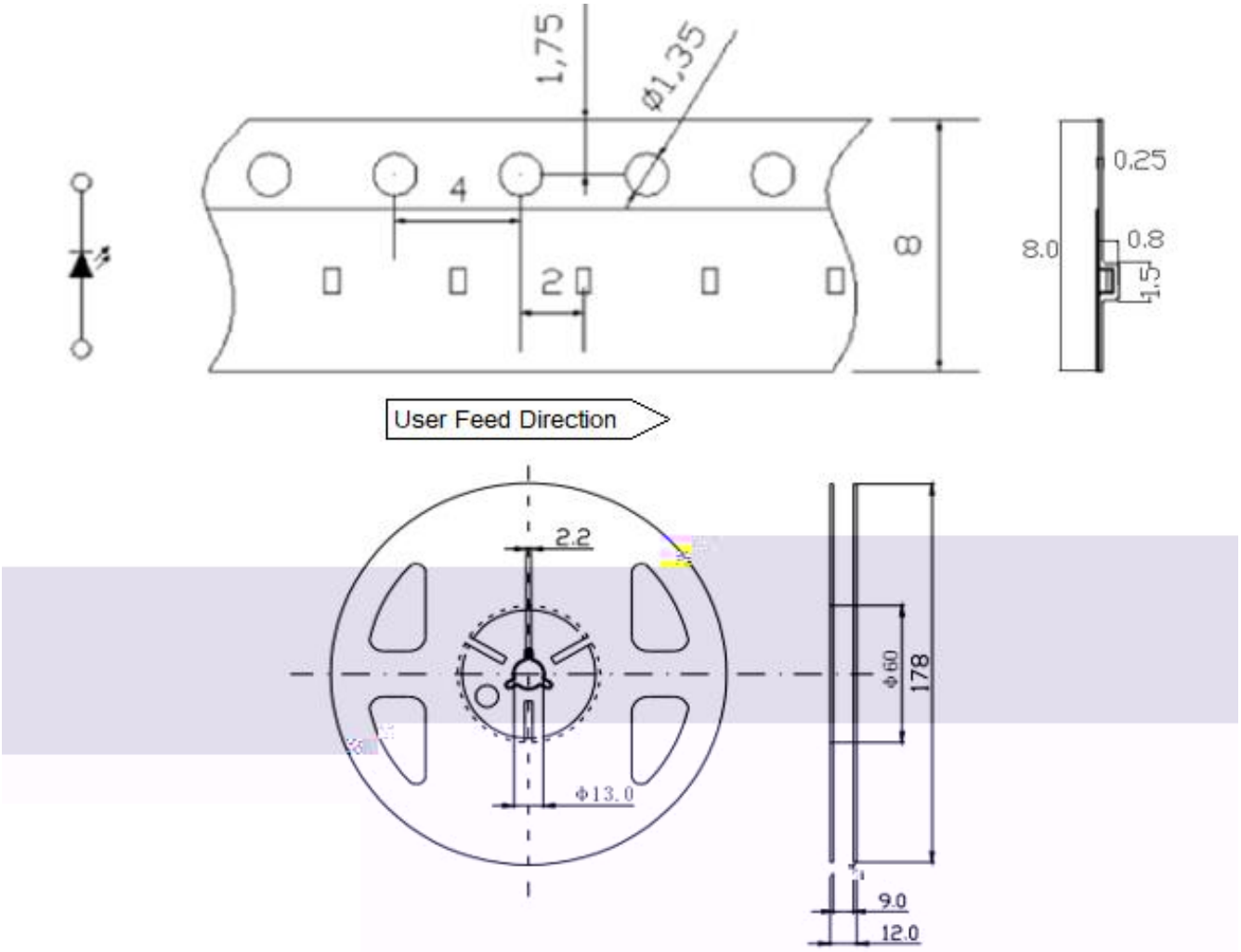
' 1.ㄚβ' ^ ~
Remarks: 1 Unit:

2.`E ' ≠ ↕ ㄐ
2. Tolerance: unless otherwise spec`i · ḫ

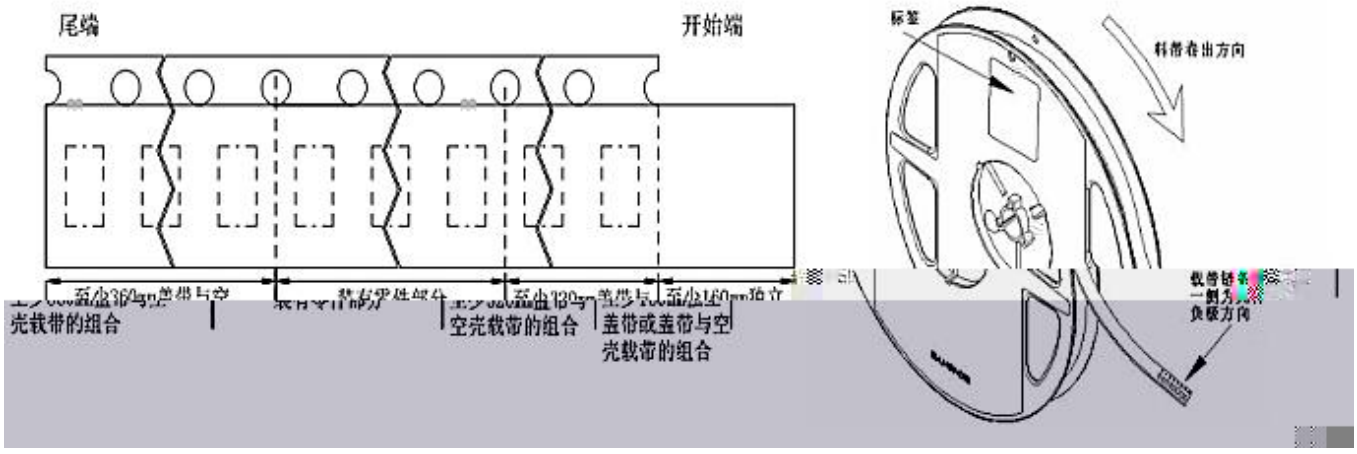
包装（1）

Packaging (1)

载带与圆盘尺寸 Belt and disk dimensions



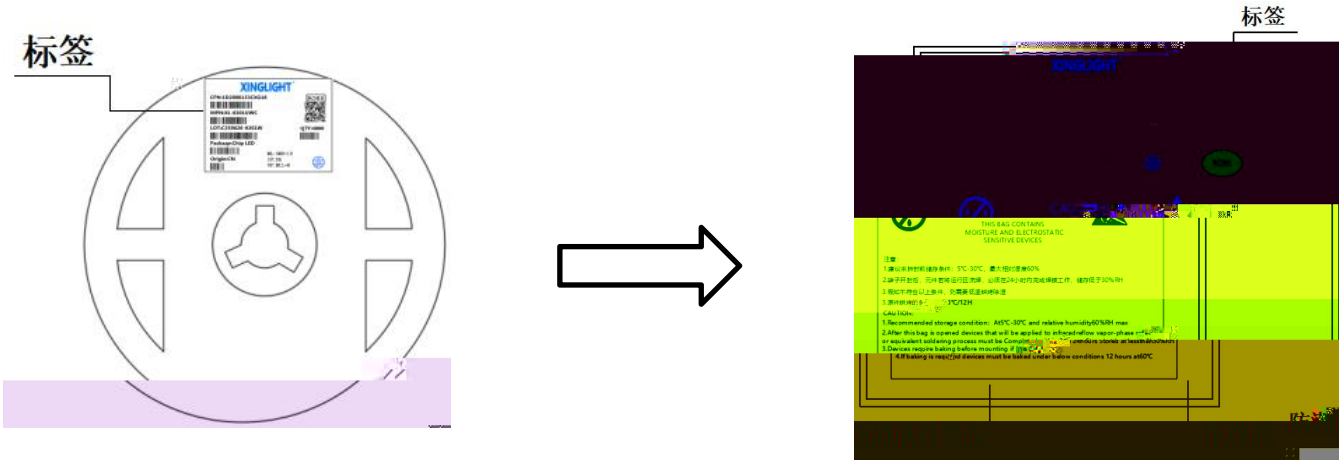
圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions



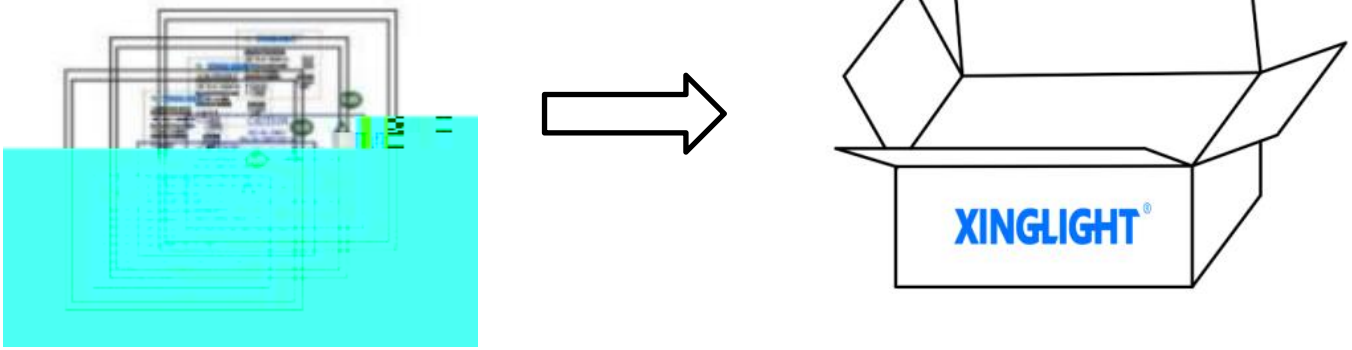
装（2）

ging (2)

Mc ure Proo d Antti-Electrostic Foil Bag



Ù Cardboard Box



Ù Label Expantion

焊接指导（1）

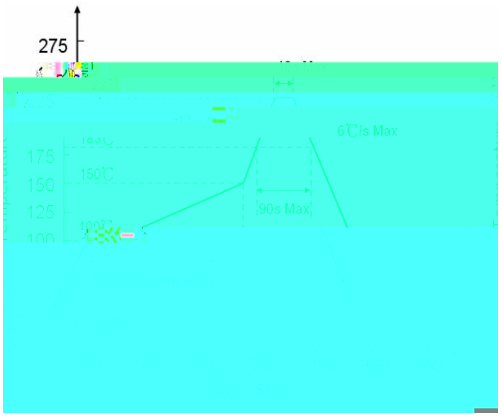
Guideline for Soldering (1)

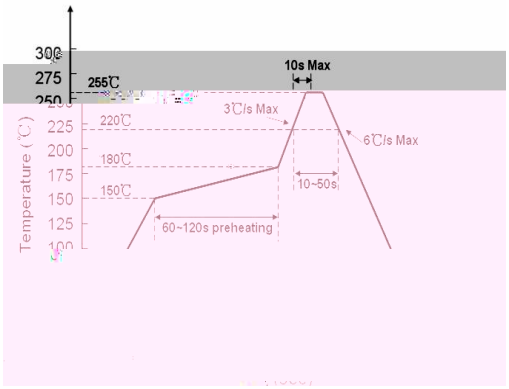
1. 使用烙铁人手焊接

Hand Soldering

2. 回流焊接：

Reflow Soldering:





2）

Guideline Soldering (2)

3. **清洗：**

Cleaning

ض U ą ˘ ض Ь G Ņ Ð Й Ņ № ˘ Ь G Ņ Ð Й Ņ

Â ą ì ɾ ³ ╕ ╟˘ ѿ ą ╕ Ь Ψ ġ № ᴴ Â

З ˘ ѿ ѡ Ь ˘ Ϩ ↕ ˆ Ė ĎĬ ᴴ Â ĺ ʳ

’ ѿ Ð Ϩ Ψ ᴴ Â

[redacted] 1)

Precautions (1)

1. **贮存：**

Storage

¥ ˚˚ ج ą ´ ˘ ㅋ˘ ˚˚ ج w̄ Ḡ Â

¥ ╟˘ ˚˚ ج ض ƀ ɢ Ņ˘ ƀ ɢ

[illegible]

[illegible]

Prec[illegible]

[illegible]

Design Consideration

[illegible]

使用注意事项（3）

Precautions (3)

4. 其他事项:

Others

Ǔ ڃ Ƀ ᵖ Ψ ˘ Ӟ ʿ G غ ˚ ج ǐ Â ˧ ʐ Ӟ

ǰ ṗ غ ˘ غ ˜ ˚ ج ɤ ˧ ʐ ˘ ≢ ˚ ج G Ӣ ᵖ عضي

Ţ Â